

SOT766-10

HLQFP176, plastic, thermal enhanced low profile quad flat package; 176 terminals; 0.5 mm pitch; 24 mm x 24 mm x 1.5 mm body

24 July 2024

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	176LQFP-EP
Package style descriptive code	QFP (quad flat package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Manufacturer package code	98ASA01825D

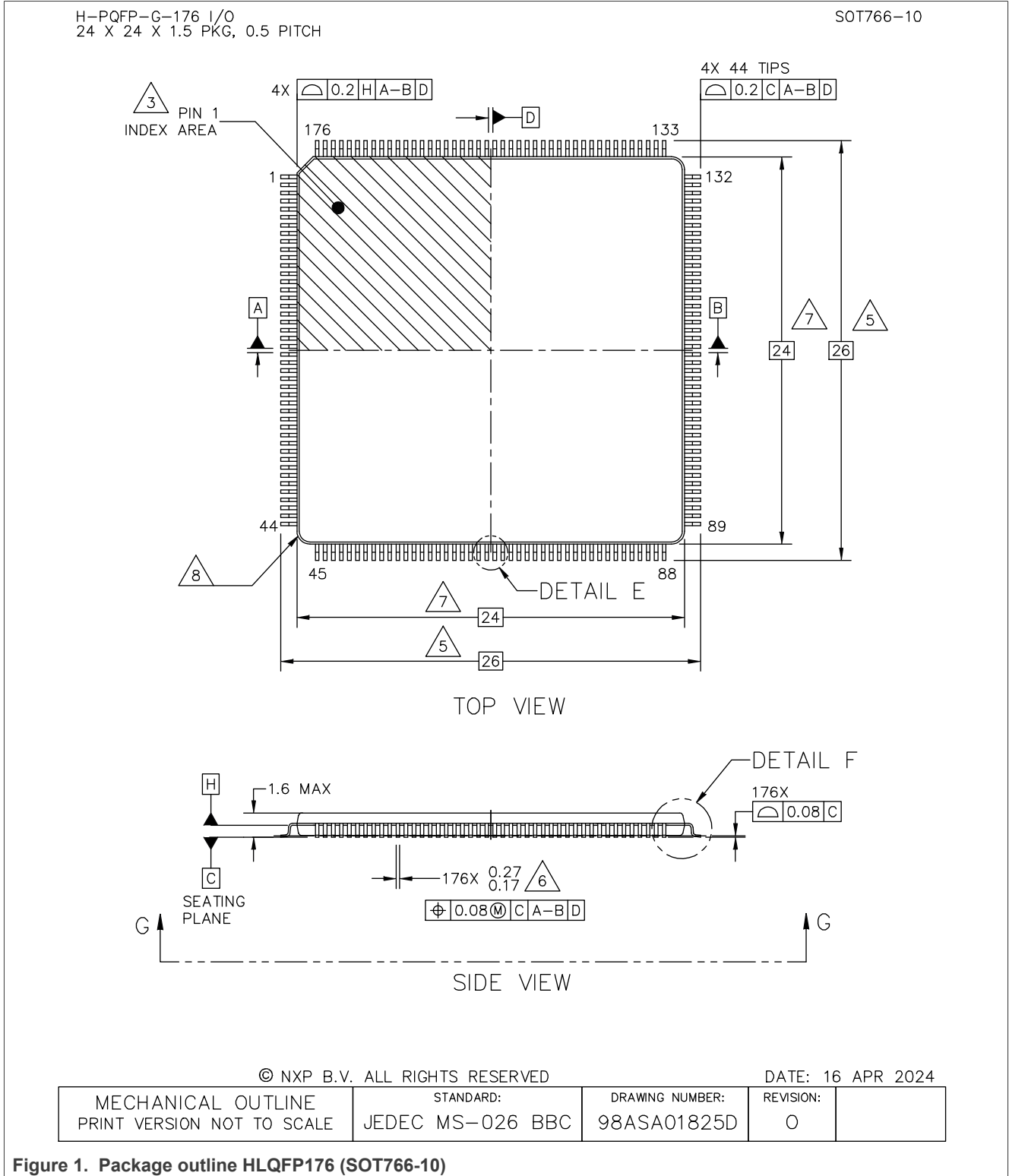
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	23.6	24	24.4	mm
package width	23.6	24	24.4	mm
seated height	-	1.5	1.6	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	176	-	

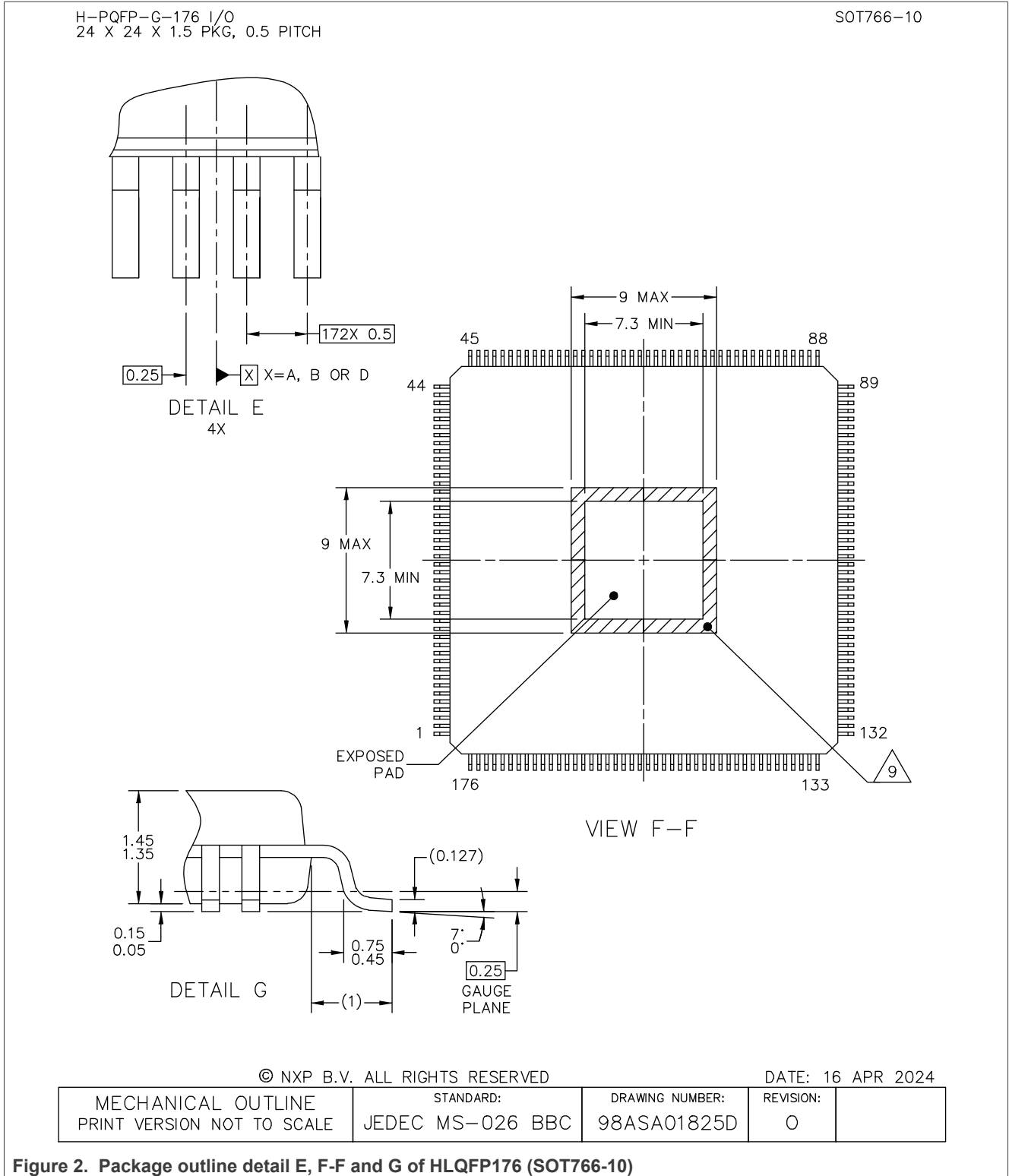


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2 Package outline

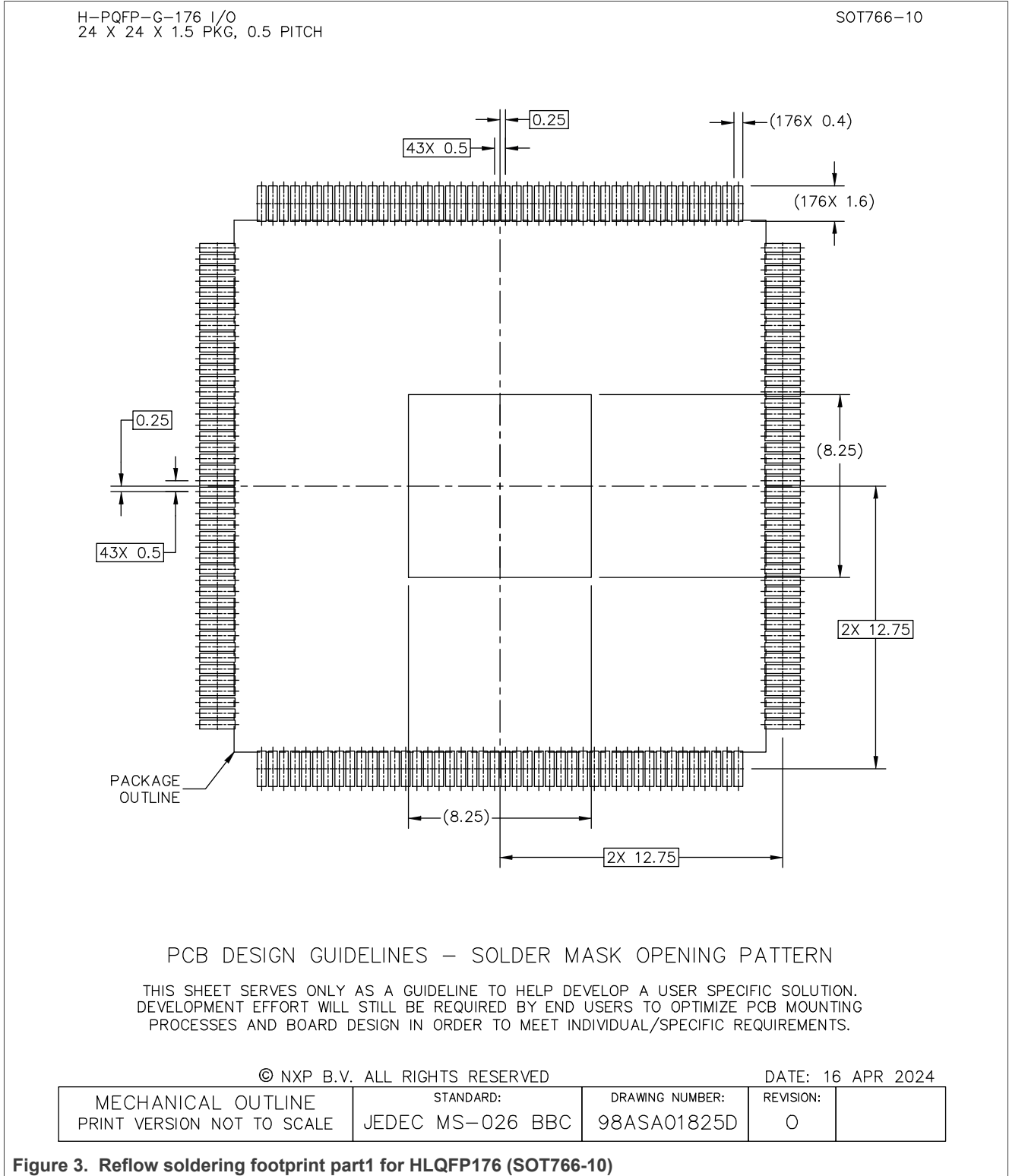


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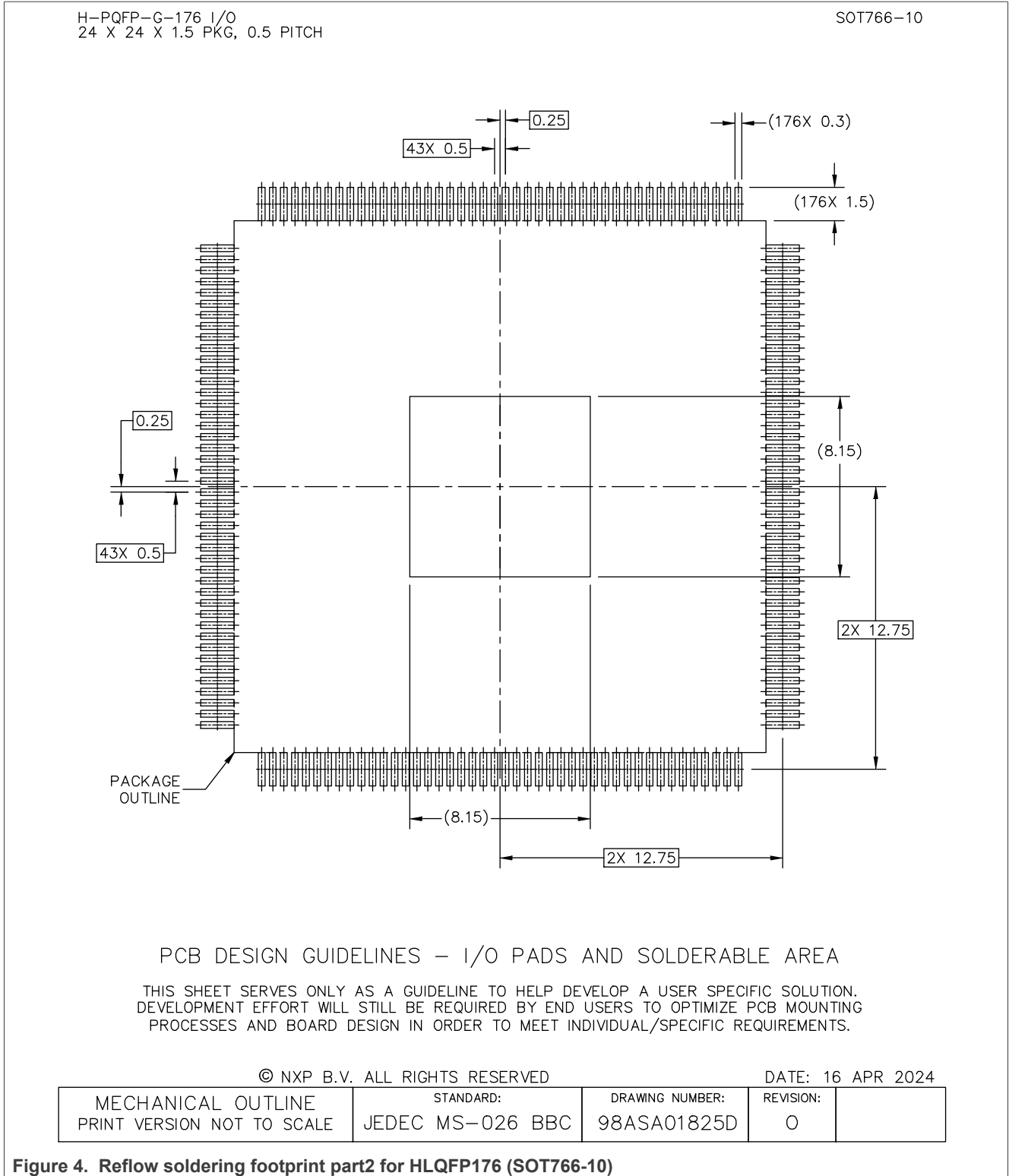


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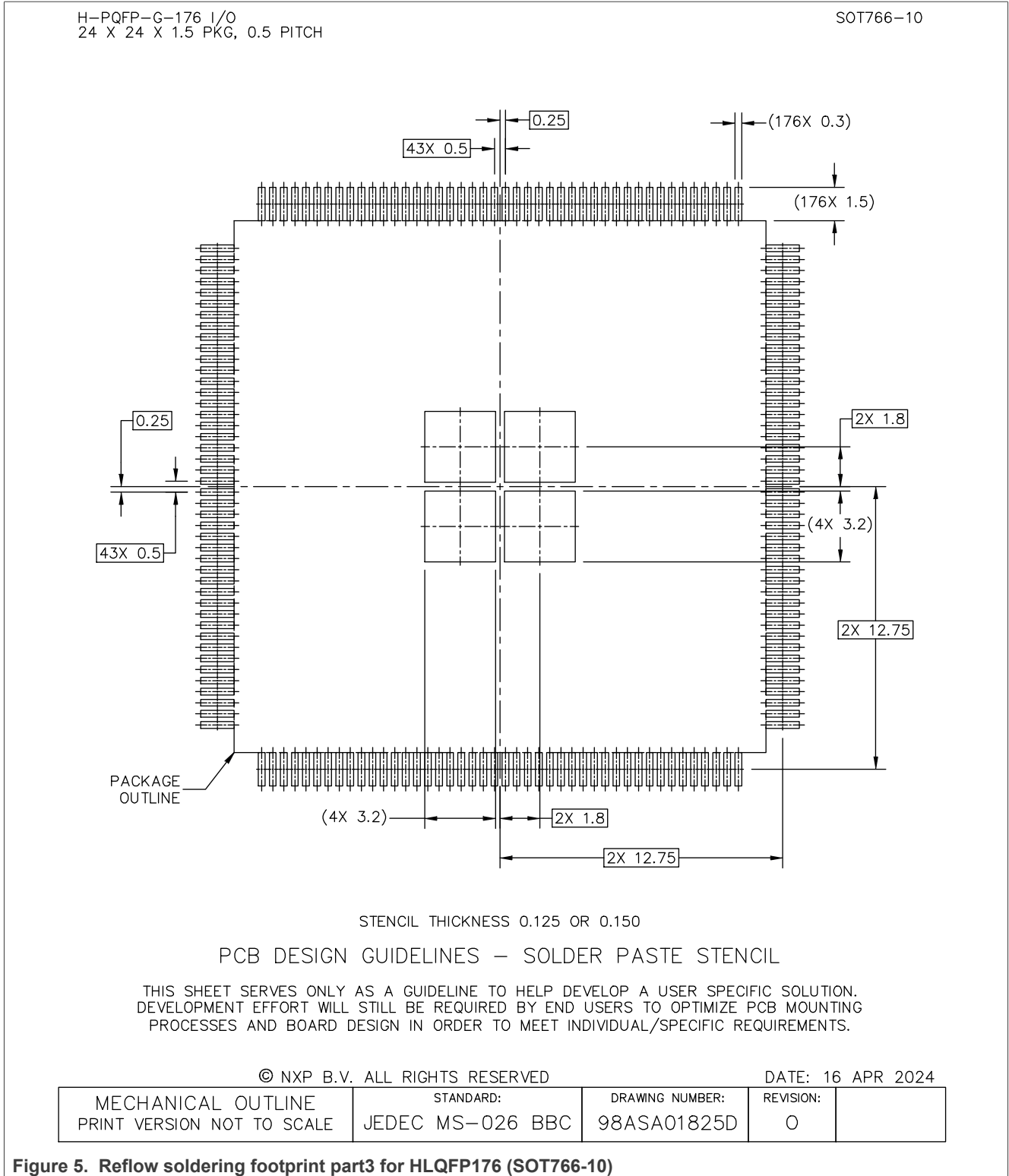
3 Soldering



HLQFP176, plastic, thermal enhanced low profile quad flat package; 176 terminals; 0.5 mm pitch;
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H-PQFP-G-176 I/O
24 X 24 X 1.5 PKG, 0.5 PITCH

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NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
5. DIMENSION TO BE DETERMINED AT SEATING PLANE C.
6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08MM AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07MM.
7. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
9. HATCHED AREA TO BE KEEP OUT ZONE FOR PCB ROUTING.

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DATE: 16 APR 2024

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: JEDEC MS-026 BBC	DRAWING NUMBER: 98ASA01825D	REVISION: 0	
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Figure 6. Package outline note HLQFP176 (SOT766-10)

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4 Legal information

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